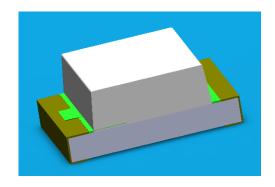
EVERLIGHT **AMERICAS**

DATASHEET

SMD B EAST20128AA0-AM



Features

- RoHS compliant
- Chip LED package.
- •Colorless clear resin.
- •Wide viewing angle 130°.
- •Brightness: 90 to 180 mcd at 20mA.
- Qualification according to AEC-Q101.
- •Precondition: Bases on JEDEC J-STD 020 Level 3.
- •Automotive reflow profile (IR reflow or wave soldering)
- •Compliance with EU REACH.
- •Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Applications

- •Automotive backlighting or indicator: Dashboard, switch, audio and video equipments...etc.
- •Backlight: LCD, switches, symbol, mobile phone and illuminated advertising.
- •Display for indoor and outdoor application.
- •Ideal for coupling into light guides.
- ·Substitution of traditional light.
- Optical indicator.
- General applications.



Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGalnP	Brilliant Orange	Water Clear

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V_{R}	12	V	
Forward Current	l _F	30	mA	
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	60	mA	
Power Dissipation	Pd	60	mW	
Junction Temperature	T _j	125	$^{\circ}\! \mathbb{C}$	
Operating Temperature	T_{opr}	-40 ~ +100	$^{\circ}\! \mathbb{C}$	
Storage Temperature	Tstg	-40 ~ +110	$^{\circ}\! \mathbb{C}$	
Thermal Resistance	Rth _{J-A}	800	K/W	
	Rth _{J-S}	450	K/W	
ESD	ESD _{HBM}	2000	V	
(Classification acc. AEC Q101)	ESD _{MM}	200	V	
Soldering Temperature	T_{sol}	Reflow Soldering : 260 $^\circ\!\!\mathbb{C}$ for 30 sec. Hand Soldering : 350 $^\circ\!\!\mathbb{C}$ for 3 sec.		



Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	90		180	mcd	I _F =20mA
Viewing Angle	$2\theta_{1/2}$		130		deg	I _F =20mA
Peak Wavelength	λр		611		nm	I _F =20mA
Dominant Wavelength	λd	603.5		609.5	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ		17		nm	I _F =20mA
Forward Voltage	V_{F}	1.75		2.35	V	I _F =20mA
Reverse Current	I _R			10	μΑ	V _R =12V
Temperature coefficient of λp	TC_{\lambdap}		0.06		nm/K	I _F =20mA
Temperature coefficient of λd	TC_{\lambdad}		0.4		nm/K	I _F =20mA
Temperature coefficient of V _F	TC _V		-2.3		mV/K	I _F =20mA

Note:

- 1. Tolerance of Luminous Intensity: ±11%
- 2. Tolerance of Dominant Wavelength: ±1nm
- 3. Tolerance of Forward Voltage: ±0.1V

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
Q2	90	112		
R1	112	140	mcd	$I_F = 20 \text{mA}$
R2	140	180		

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
D9	603.5	606.5		I _F =20mA
D10	606.5	609.5	— nm	

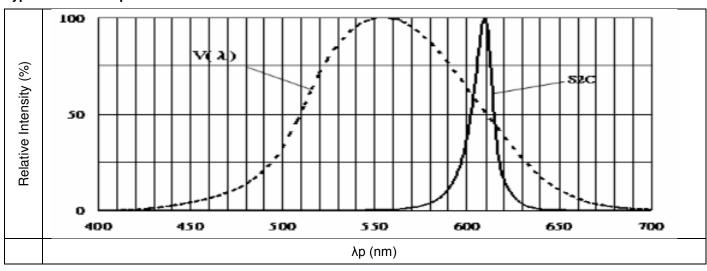
Note:

Tolerance of Dominant Wavelength: ±1nm



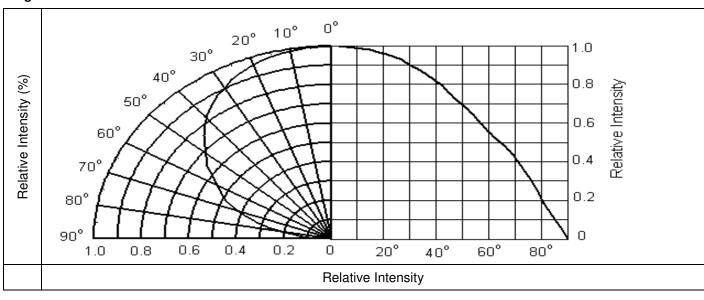
Typical Electro-Optical Characteristics Curves

Typical Curve of Spectral Distribution

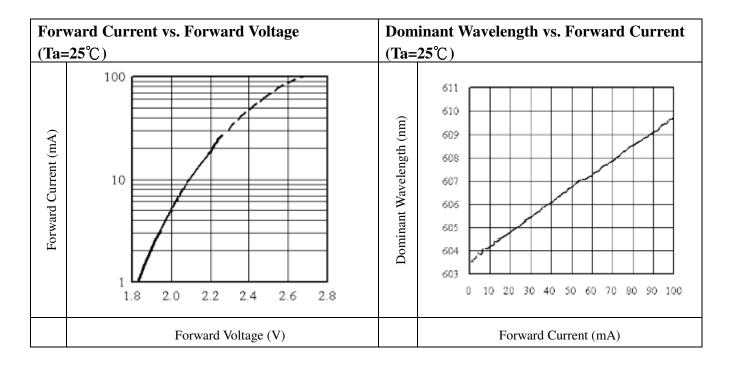


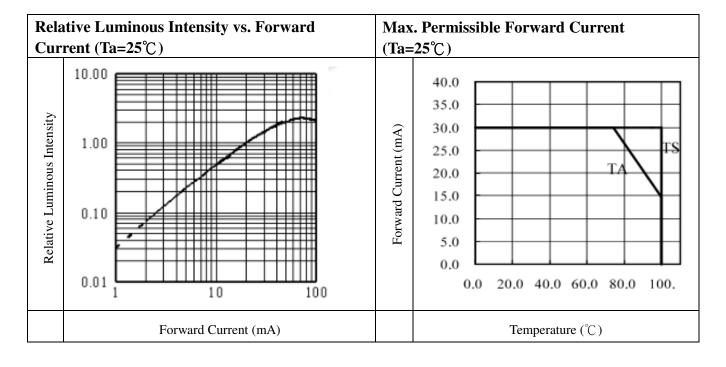
Note: $V(\lambda)$ =Standard eye response curve; I_F =20mA

Diagram Characteristics of Radiation

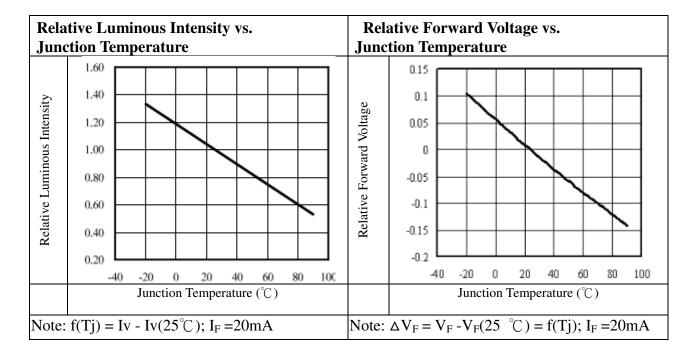






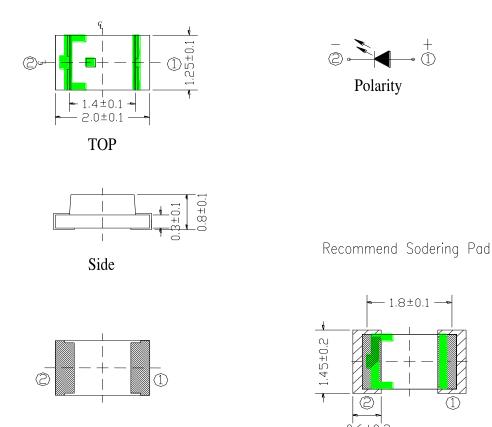








Package Dimension



Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Bottom



Moisture Resistant Packing Materials

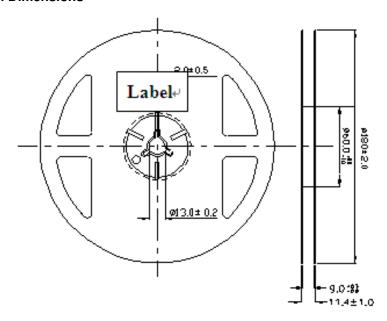
Label Explanation



Label Explanation

- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

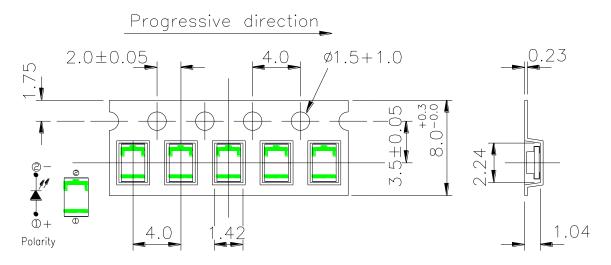
Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

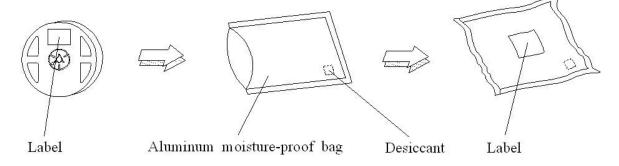


Carrier Tape Dimensions: Loaded Quantity 3000 pcs Per Reel



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process

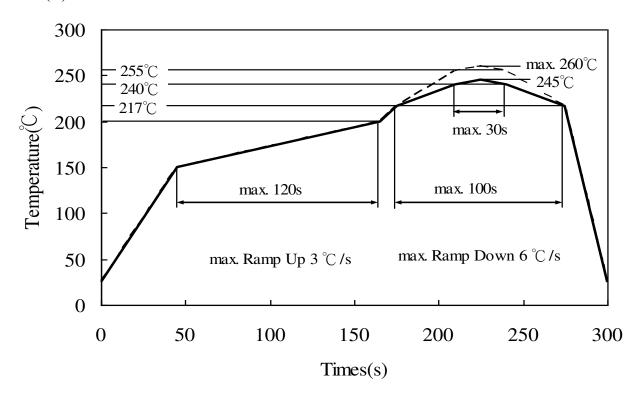


Note: Tolerances unless mentioned ±0.1mm. Unit = mm

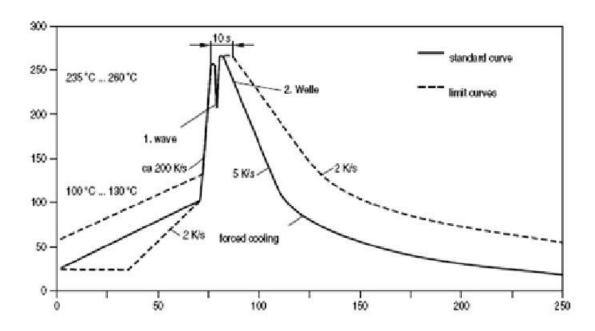


Precautions for Use

1. Soldering Condition (Reference: IPC/JEDEC J-STD-020D)
(A)IR reflow

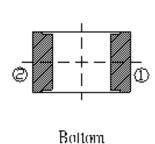


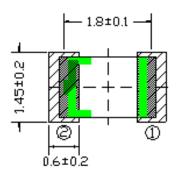
(B) Wave Soldering reflow





(B) Recommend soldering pad





Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

- 3.1 Moisture proof bag should only be opened immediately prior to usage.
- 3.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.
- 3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
- 3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 25 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350° C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.

Application Restrictions

1. High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight Americas before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.